Abstract

This invention relates to a method for bonding of a first substrate (3) to a second substrate (8) on contact surfaces (3k, 8k) of the substrates (3, 8) with the following steps, especially the following sequence:

- accommodating the first substrate (3) on a first receiving surface (2o) of a first receiving apparatus (1) and receiving the second substrate (8) on a second receiving surface (2o') of a second receiving apparatus (4),
- contact-making of the contact surfaces (3k, 8k) at a bond initiation site (20),
- bonding the first substrate (3) to the second substrate (8) along a bonding wave which is travelling from the bond initiation site (20) to the side edges (3s, 8s) of the substrates (3, 8),

characterized in that the first substrate (3) and/or the second substrate (8) is/are deformed for alignment of the contact surfaces (3k, 8k) outside the bond initiation site (20) before and/or during the bonding.

Furthermore the invention relates to a corresponding device.

Figure 6 in this regard